L Number	Hits	Search Text	DB	Time stamp
1	2	("6313532").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:05
2	73	inoue-kosuke.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:16
3	11	tenmei-hiroyuki.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:18
4	86	yamaguchi-yoshihide.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:20
6	36	hozoji-hiroshi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:21
7	118	Tsunoda-shigeharu.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:21
8	22	minagawa-madoka.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:22
9	36	kanda-naoya.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:22
13	31	ujiie-kenji.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:24
12	51	yajima-akira.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:25
11	397	nishimura-asao.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:26
5	13	oroku-noriyuki.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:32
10	159	anjo-ichiro.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:34

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14	13	257/777-783.ccls. and insulat$4 and protrus$4 and inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:36
15	12	257/787,792-793,784.ccls. and insulat$4 and protrus$4 and inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:37
16	12	257/668,701,737-738.ccls. and insulat$4 and protrus$4 and inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:38
17	6	257/734,759,773.ccls. and insulat$4 and protrus$4 and inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:07
19	68	(insulat$4 dielectric) with protrus$4 with inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:44
20	5870	(insulat$4 dielectric) with inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:44
21	83	(insulat$4 dielectric) with inclin$4 and (bump ball) and (IC chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:58
22	33	257/734,759,773.ccls. and (insulat$4 dielectric) with protrus$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:39
24	532	(insulat$4 dielectric) with protrus$4 and inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:48
25	633	257/$.ccls. and (insulat$4 dielectric) with protrus$4 and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:50
26	12	("4025411" | "4073054" | "4180432" | "4451326" | "4466177" | "4470874" | "4481070" | "4515652" | "4539744" | "4543597" | "4545852" | "4594769").PN.	USPAT	2003/07/31 17:02